

Title (en)  
PROCESSES OF FINISHING SLITS OF SURFACE LAYER OF AIRPLANE RUNWAY

Title (de)  
VERFAHREN ZUM VERFÜLLEN VON FUGEN DER OBERFLÄCHENSCHICHT VON LANDEBAHNEN

Title (fr)  
PROCEDES POUR RETOUCHER LES FENTES DE LA COUCHE SUPERFICIELLE D'UNE PISTE D'AVIATION

Publication  
**EP 1337711 A4 20050413 (EN)**

Application  
**EP 00980259 A 20001114**

Priority  
US 0030137 W 20001114

Abstract (en)  
[origin: WO0240806A2] A process is designed to finish all slits of the surface layer of an airplane runway. The process involves a first step in which a slit is heated such that the surface of the slit is dry, and that the capillary holes of the slit are opened up. The surface of the slit is then provided with a coating of an asphalt synthetic agent. The coating is subsequently heated to cause the molecules of the asphalt synthetic agent to diffuse into the capillary holes of the slit, thereby preventing the water from finding its way into the gradation layer of the runway. In the meantime, the slit is provided with a soft interface capable of preventing the water from finding its way into the slits of the surface layer of the runway. The soft interface is securely attached to the slits regardless of the climatic changes.  
[origin: WO0240806A2] A process of finishing slits in the surface layer of a runway involves a first step in which a slit (11) is heated such that the surface of the slit (11) is dry, and that the capillary holes of the slit (11) are opened up. The surface of the slit (11) is then provided with a coating (50) of an asphalt synthetic agent. The coating (50) is subsequently heated to cause the molecules of the asphalt synthetic agent to diffuse into the capillary holes of the slit (11), thereby preventing water from finding its way into the gradation layer (A) of the runway. The slit (11) is provided with a soft interface (60) capable of preventing the water from finding its way into the slits of the surface layer of the runway. The soft interface (60) is securely attached to the slits.

IPC 1-7  
**E01C 11/02**; **E01C 11/00**; **E01C 11/10**; **E01C 23/09**; **E04B 1/68**; **E04F 15/14**

IPC 8 full level  
**E01C 11/00** (2006.01); **E01C 11/10** (2006.01); **E01C 23/00** (2006.01); **E01C 23/09** (2006.01); **E04B 1/68** (2006.01); **E04F 15/14** (2006.01)

CPC (source: EP)  
**E01C 11/005** (2013.01); **E01C 11/10** (2013.01); **E01C 23/0966** (2013.01); **E04B 1/68** (2013.01); **E04B 1/6801** (2013.01); **E04F 15/14** (2013.01)

Citation (search report)

- [A] US 5236276 A 19930817 - CHANG CHUNG-HSIUNG [TW], et al
- [A] US 4324504 A 19820413 - COTTINGHAM RICHARD L, et al
- See references of WO 0240806A2

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CN105625150A; CN112267344A; CN110904763A

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**WO 0240806 A2 20020523**; **WO 0240806 A3 20021107**; AT E374865 T1 20071015; AU 1754401 A 20020527; BR 0017373 A 20031209; CA 2428367 A1 20020523; CA 2428367 C 20070731; CN 1479826 A 20040303; DE 60036648 D1 20071115; EP 1337711 A2 20030827; EP 1337711 A4 20050413; EP 1337711 B1 20071003; EP 1337711 B8 20080123; IL 155877 A0 20031223; JP 2004514077 A 20040513; MX PA03004260 A 20030922

DOCDB simple family (application)  
**US 0030137 W 20001114**; AT 00980259 T 20001114; AU 1754401 A 20001114; BR 0017373 A 20001114; CA 2428367 A 20001114; CN 00820014 A 20001114; DE 60036648 T 20001114; EP 00980259 A 20001114; IL 15587700 A 20001114; JP 2002543107 A 20001114; MX PA03004260 A 20001114